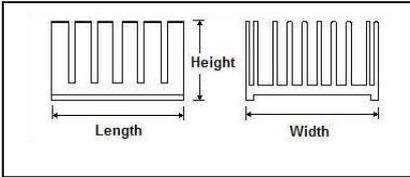
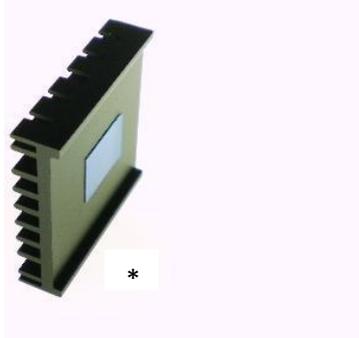




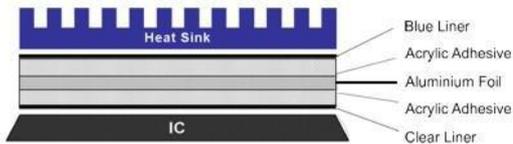
## Flip Chip



**All ABL's BGA heatsinks are supplied with thermal tape**

| Model       | Width | Length | Height | Pad Size | Anodised Finish | °C/W    | °C/W        | Wire Form   |
|-------------|-------|--------|--------|----------|-----------------|---------|-------------|-------------|
|             | [mm]  | [mm]   | [mm]   | [mm]     |                 | Natural | Forced 2M/s |             |
| *BGA-FC-010 | 40    | 40     | 10.0   | 20x20    | Black           | 13.50   | 7.00        | WF700/WF300 |
| BGA-FC-015  | 40    | 40     | 24.0   | 30x30    | Black           | 11.00   | 5.50        | WF700/WF300 |

### Thermally Conductive Aluminium Foil



All ABL's BGA heatsinks are supplied with thermal tape.

With excellent thermal conductivity, cushioning and gap filling properties, the pad is an ideal thermal interface material specifically designed for heat sink attachment to MPU, chip set and other plastic encapsulated components.

It consists of an aluminium foil backing coated, on both sides, with a very high temperature resistance acrylic adhesive. Due to its high heat performance and adhesive properties this tape can also be used to attach components to a vertical heatsink and to metal enclosure surfaces.

|                           |                       |                                     |
|---------------------------|-----------------------|-------------------------------------|
| Colour                    | -                     | White                               |
| Backing Type / Thickness  | Mm                    | Aluminium Foil / 0.10               |
| Adhesive Type / Thickness | Mm                    | Acrylic 0.075 (on clear liner side) |
| Total Thickness           | mm                    | 0,27                                |
| Adhesion                  | Kg/25mm               | 1,5                                 |
| Thermal Conductivity      | W/m-K                 | 0,95                                |
| Thermal Resistance        | °C-in <sup>2</sup> /W | 0,2                                 |
| Holding Power @ 23°C      | Hour                  | >72                                 |
| Holding Power @ 130°C     | Hour                  | >2                                  |